Application No.: 10/763,859 Attorney Docket: AMKOR-053G

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:	Tae Heon Lee)	Confirmation No.	8528
Serial No.:	10/763,859)	Art Unit:	2814
Filed:	01/23/2004)	Examiner:	Cao, Phat X.
For:	Semiconductor Reduced Thickne	Package	Having)		

AMENDMENT AFTER ALLOWANCE UNDER 37 C.F.R. §1.312

Mail Stop Issue Fee Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir/Madam:

A Notice of Allowance was mailed by the U.S. Patent and Trademark Office in relation to the above-identified patent application on May 4, 2006. Since Applicant has not yet paid the issue fee in relation to the present application, in accordance with the provisions of 37 C.F.R. §1.312(a), Applicant respectfully requests that the application be amended as follows:

Amendments to the Specification begin on page 2 of this paper; and Remarks begin on page 3 of this paper.